FAIRCHILD SEMICONDUCTOR®

November 2002

ISL9R1560G2, ISL9R1560P2, ISL9R1560S2, ISL9R1560S3S

15A, 600V Stealth™ Diode

General Description

The ISL9R1560G2, ISL9R1560P2, ISL9R1560S2 and ISL9R1560S3S are Stealth™ diodes optimized for low loss performance in high frequency hard switched applications. The Stealth™ family exhibits low reverse recovery current ($I_{RM(REC)}$) and exceptionally soft recovery under typical operating conditions.

This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low $I_{RM(REC)}$ and short t_a phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the Stealth™ diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

Formerly developmental type TA49410.

Features

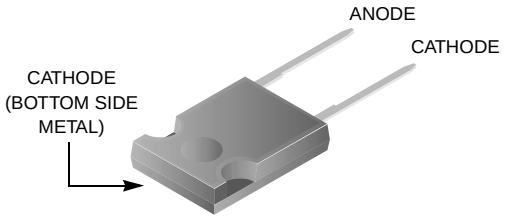
- Soft Recovery . . . . . $t_b / t_a > 1.2$
- Fast Recovery . . . . . $t_{rr} < 30ns$
- Operating Temperature . . . . . 175^oC
- Reverse Voltage 600V
- Avalanche Energy Rated

Applications

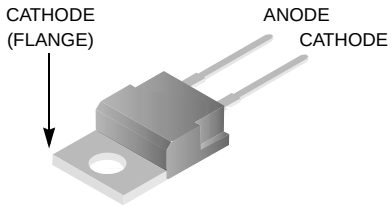
- Switch Mode Power Supplies
- Hard Switched PFC Boost Diode
- UPS Free Wheeling Diode
- Motor Drive FWD
- SMPS FWD
- Snubber Diode

Package

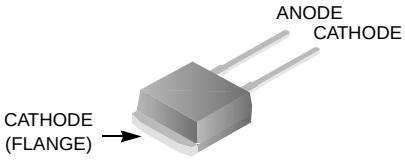
JEDEC STYLE TO-247



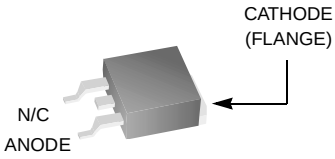
JEDEC TO-220AC



JEDEC STYLE TO-262



JEDEC TO-263AB



Symbol



Device Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{RRM}	Repetitive Peak Reverse Voltage	600	V
V_{RWM}	Working Peak Reverse Voltage	600	V
V_R	DC Blocking Voltage	600	V
$I_{F(AV)}$	Average Rectified Forward Current (T_C = 145°C)	15	A
I_{FRM}	Repetitive Peak Surge Current (20kHz Square Wave)	30	A
I_{FSM}	Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60Hz)	200	A

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Symbol	Parameter	Ratings	Units
P_D	Power Dissipation	150	W
E_{AVL}	Avalanche Energy (1A, 40mH)	20	mJ
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 175	°C
T_L	Maximum Temperature for Soldering		
T_{PKG}	Leads at 0.063in (1.6mm) from Case for 10s	300	°C
	Package Body for 10s, See Techbrief TB334	260	°C

CAUTION: Stresses above those listed in "Device Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Package Marking and Ordering Information

Device Marking	Device	Package	Tape Width	Quantity
R1560G2	ISL9R1560G2	TO-247	N/A	30
R1560P2	ISL9R1560P2	TO-220AC	N/A	50
R1560S2	ISL9R1560S2	TO-262	N/A	50
R1560S3S	ISL9R1560S3S	TO-263AB	24mm	800

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min	Typ	Max	Units
Off State Characteristics							
I_R	Instantaneous Reverse Current	V_R = 600V	T_C = 25°C	-	-	100	µA
			T_C = 125°C	-	-	1.0	mA
On State Characteristics							
V_F	Instantaneous Forward Voltage	I_F = 15A	T_C = 25°C	-	1.8	2.2	V
			T_C = 125°C	-	1.65	2.0	V
Dynamic Characteristics							
C_J	Junction Capacitance	V_R = 10V, I_F = 0A		-	62	-	pF
Switching Characteristics							
t_{rr}	Reverse Recovery Time	I_F = 1A, dI_F/dt = 100A/µs, V_R = 30V		-	25	30	ns
		I_F = 15A, dI_F/dt = 100A/µs, V_R = 30V		-	35	40	ns
t_{rr}	Reverse Recovery Time	I_F = 15A, dI_F/dt = 200A/µs, V_R = 390V, T_C = 25°C		-	29.4	-	ns
$I_{RM(REC)}$	Maximum Reverse Recovery Current			-	3.5	-	A
Q_{RR}	Reverse Recovered Charge			-	57	-	nC
t_{rr}	Reverse Recovery Time	I_F = 15A, dI_F/dt = 200A/µs, V_R = 390V, T_C = 125°C		-	90	-	ns
S	Softness Factor (t_b/t_a)			-	2.0	-	
$I_{RM(REC)}$	Maximum Reverse Recovery Current			-	5.0	-	A
Q_{RR}	Reverse Recovered Charge			-	275	-	nC
t_{rr}	Reverse Recovery Time	I_F = 15A, dI_F/dt = 800A/µs, V_R = 390V, T_C = 125°C		-	52	-	ns
S	Softness Factor (t_b/t_a)			-	1.36	-	
$I_{RM(REC)}$	Maximum Reverse Recovery Current			-	13.5	-	A
Q_{RR}	Reverse Recovered Charge			-	390	-	nC
dI_M/dt	Maximum di/dt during t_b			-	800	-	A/µs
Thermal Characteristics							
$R_{\theta JC}$	Thermal Resistance Junction to Case			-	-	1.0	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-247		-	-	30	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-220		-	-	62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-262		-	-	62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-263		-	-	62	°C/W

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Typical Performance Curves

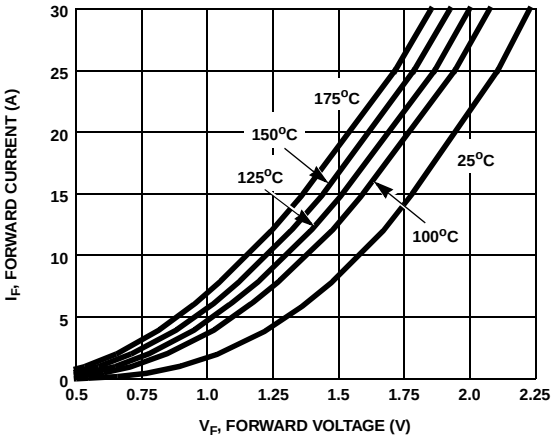


Figure 1. Forward Current vs Forward Voltage

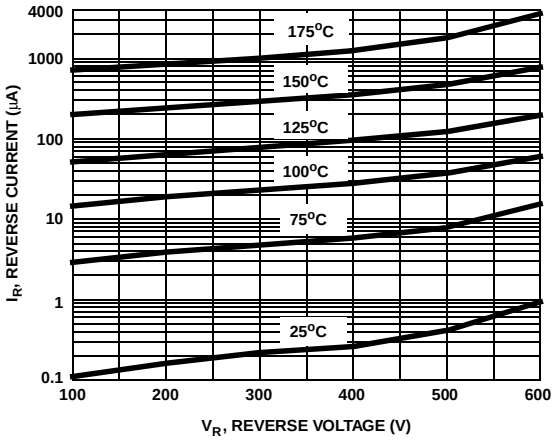


Figure 2. Reverse Current vs Reverse Voltage

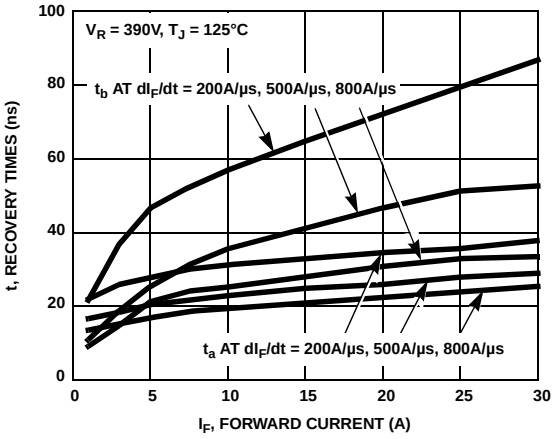


Figure 3. t_a and t_b Curves vs Forward Current

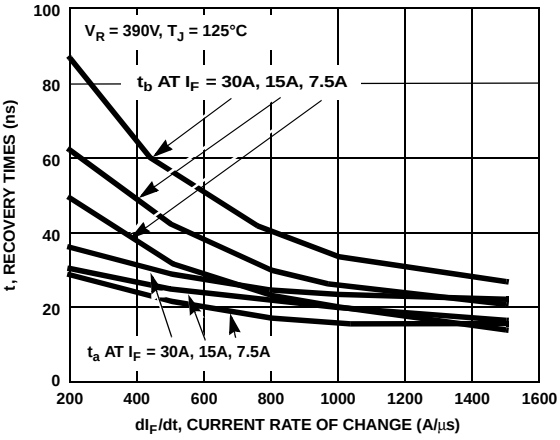


Figure 4. t_a and t_b Curves vs dI_F/dt

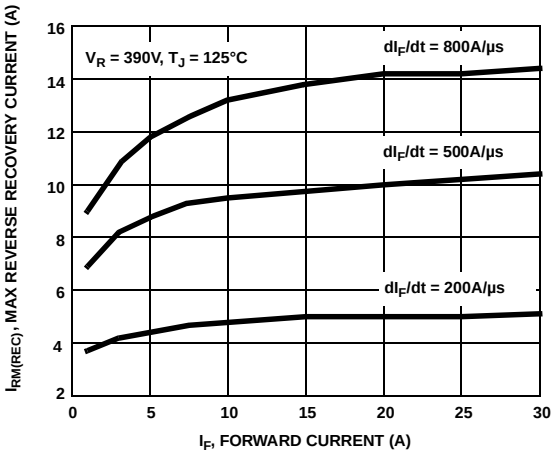


Figure 5. Maximum Reverse Recovery Current vs Forward Current

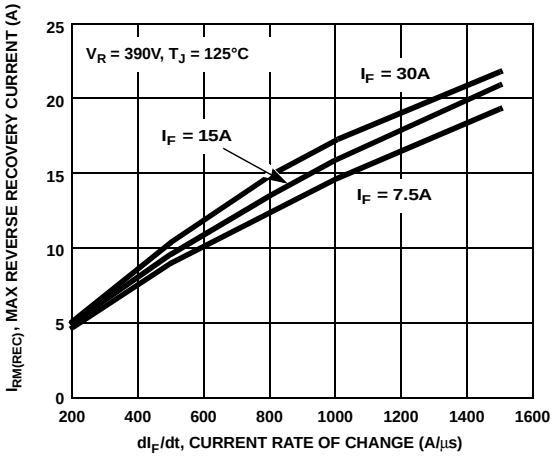


Figure 6. Maximum Reverse Recovery Current vs dI_F/dt

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Typical Performance Curves (Continued)

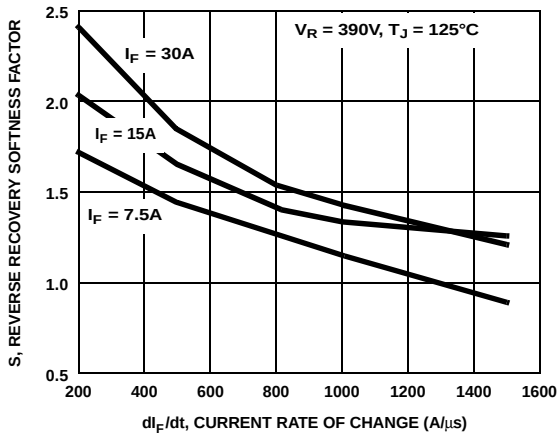


Figure 7. Reverse Recovery Softness Factor vs dI_F/dt

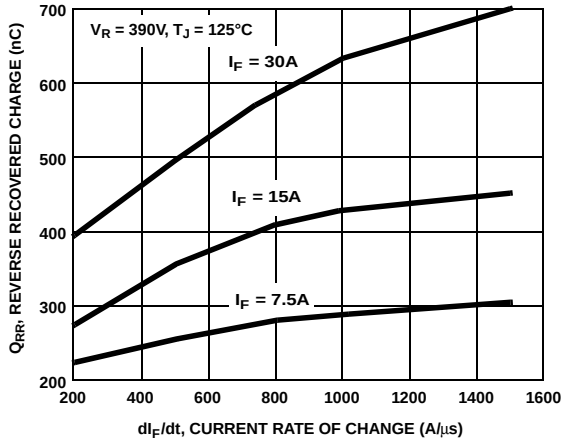


Figure 8. Reverse Recovered Charge vs dI_F/dt

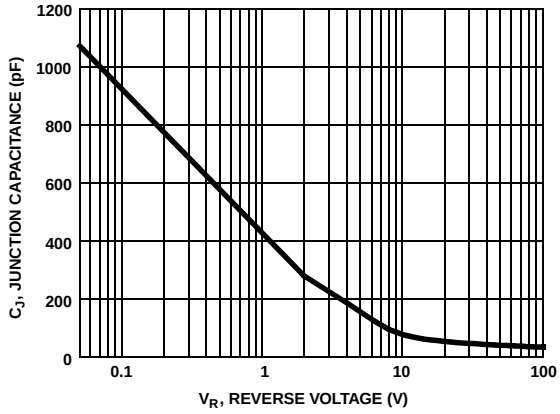


Figure 9. Junction Capacitance vs Reverse Voltage

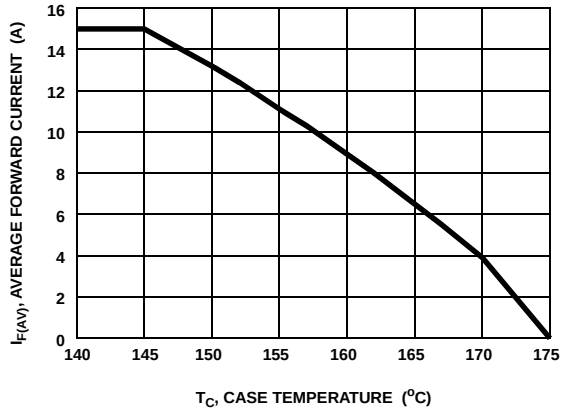


Figure 10. DC Current Derating Curve

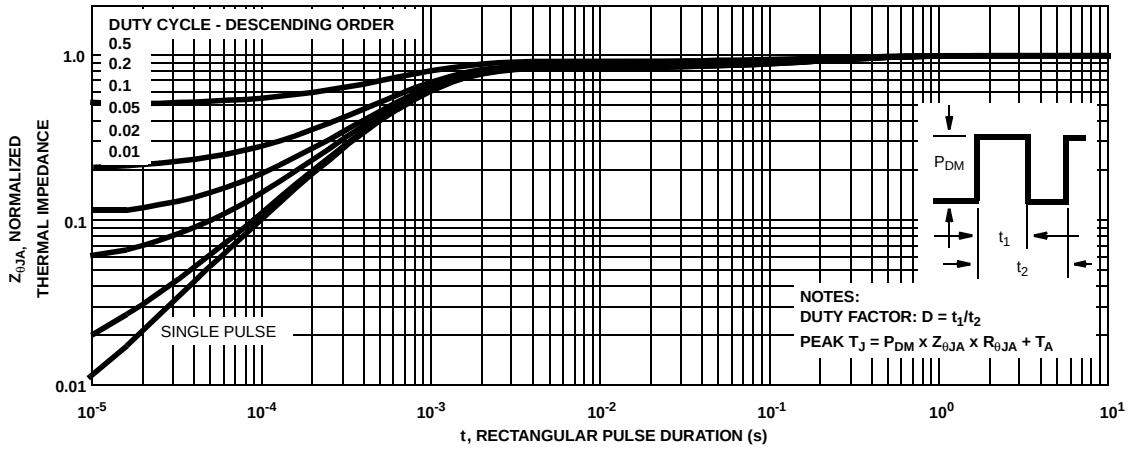


Figure 11. Normalized Maximum Transient Thermal Impedance

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Test Circuit and Waveforms

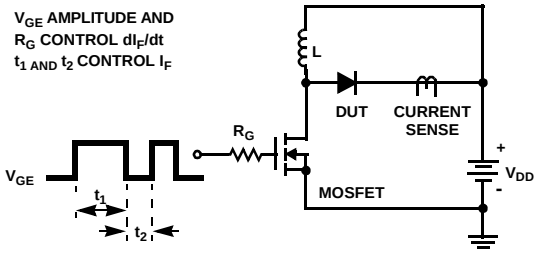


Figure 12. t_{rr} Test Circuit

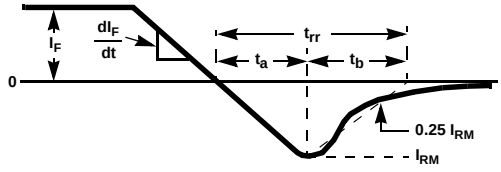


Figure 13. t_{rr} Waveforms and Definitions

I = 1A
L = 40mH
R < 0.1Ω
V_{DD} = 50V
$E_{AVL} = 1/2LI^2 [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]$
Q_1 = IGBT (BV_{CES} > DUT $V_{R(AVL)}$)

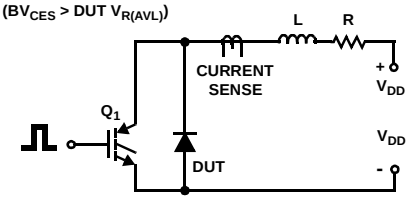


Figure 14. Avalanche Energy Test Circuit

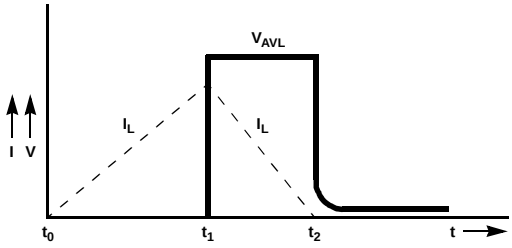


Figure 15. Avalanche Current and Voltage Waveforms

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CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	QS™	SyncFET™
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